

Electrostatic Discharged Protection Devices (ESD) Data Sheet

Description

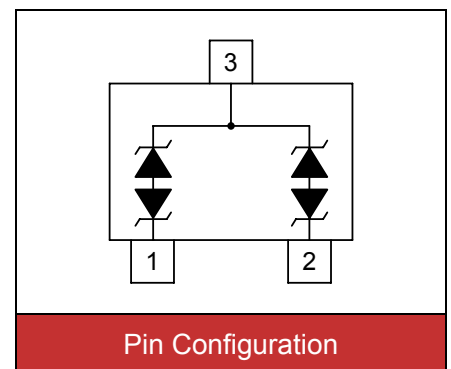
This is ultra low capacitance TVS arrays designed to protect high speed data interfaces. It has been specifically designed to protect sensitive components which is connected to high-speed data and transmission lines from overvoltage caused by electrostatic (ESD), cable discharge events (CDE) and electrical fast transients (EFT).



Contact : ±8kV
Air : ±15kV

Features

- IEC61000-4-2 ESD 15KV Air, 8KV contact compliance
- SOT-523 surface mount package
- Protects two high speed data lines
- Working voltage: 5V
- Low capacitance and clamping voltages
- Low leakage current
- Solid-state silicon avalanche technology
- Lead Free/RoHS compliant
- Solder reflow temperature: Pure Tin-Sn, 260~270°C
- Flammability rating UL 94V-0
- Meets MSL level 1, per J-STD-020
- Marking: 5E



Applications

- HDMI interface protection
- Mobile display digital interface
- RF/Antenna circuits
- USB 2.0 & Firewire ports
- GaAs photodetector protection
- HBT power Amp protection
- Infiniband transceiver protection

Maximum Ratings

Rating	Symbol	Value	Unit
ESD voltage (Contact discharge)	V_{ESD}	±8	kV
ESD voltage (Air discharge)		±15	
Storage & operating temperature range	T_{STG}, T_J	-55~+150	°C

Electrical Characteristics ($T_J=25^{\circ}\text{C}$)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Reverse stand-off voltage	V_{RWM}				5	V
Reverse breakdown voltage	V_{BR}	$I_{BR}=1\text{mA}$	6			V
Reverse leakage current	I_R	$V_R=5\text{V}$ Each I/O pin			1	μA
Clamping voltage ($t_p=8/20\mu\text{s}$)	V_C	$I_{PP}=1\text{A}$			16	V
Off state junction capacitance	C_J	0Vdc, $f=1\text{MHz}$ Between I/O pins and GND		10		pF

Typical Characteristics Curves

Figure 1. Power Derating Curve

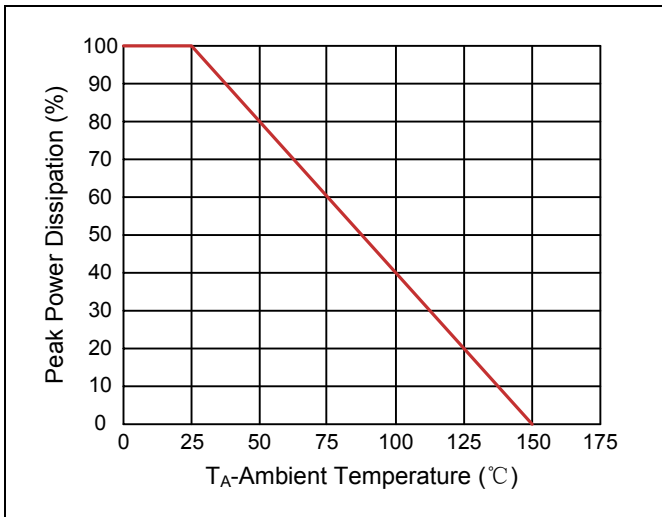


Figure 2. Pulse Waveforms

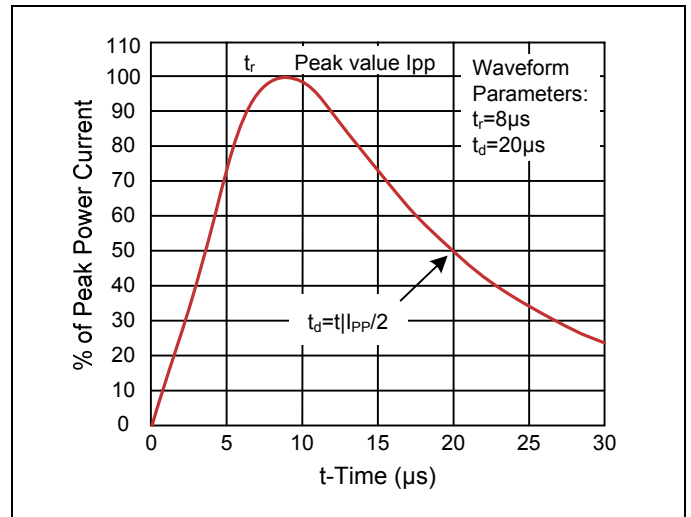


Figure 3. Capacitance vs. Reverse Voltage

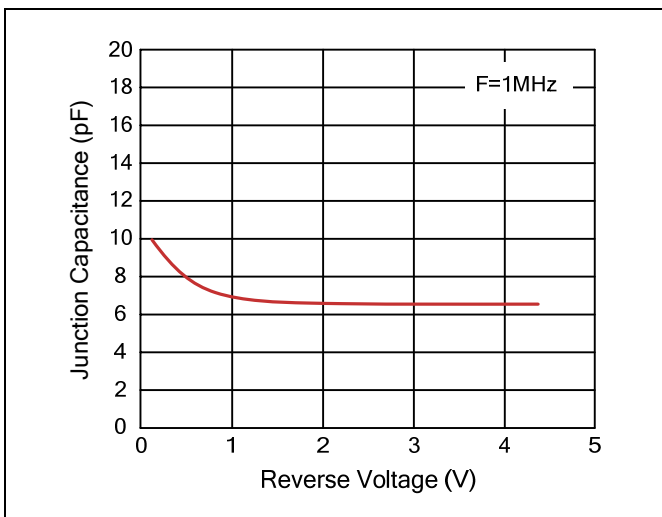
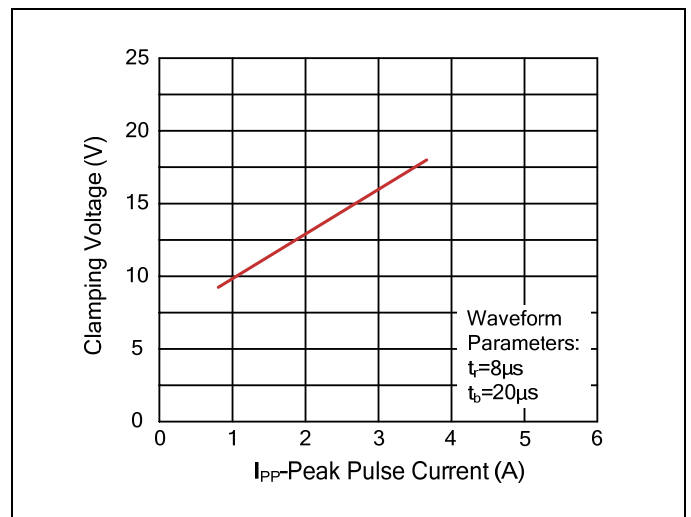
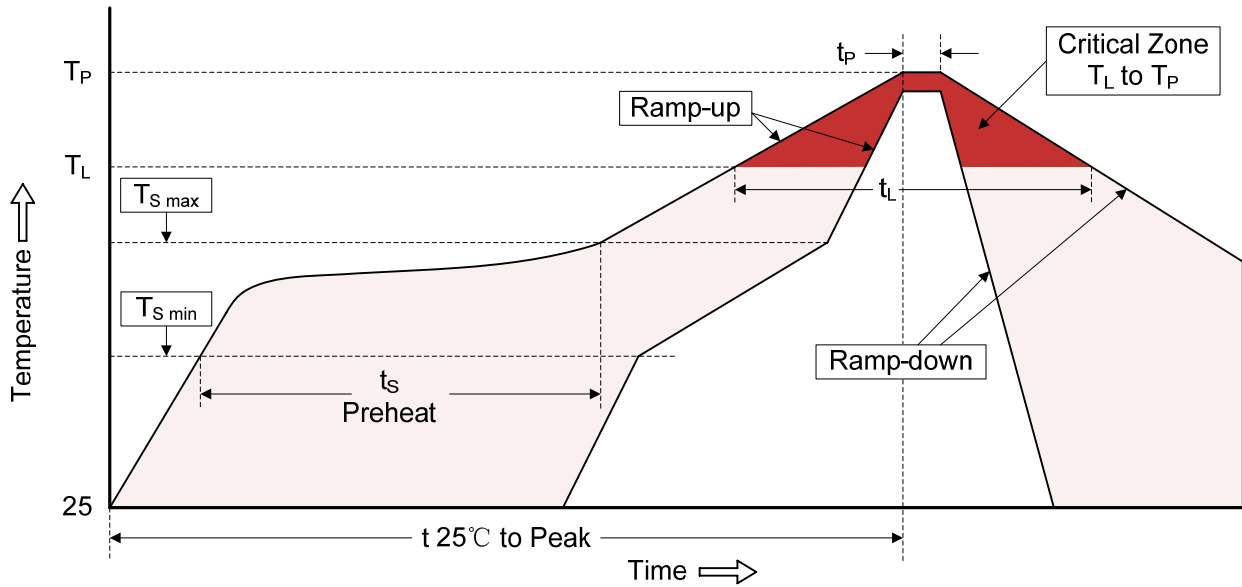


Figure 4. Clamping Voltage vs. Peak Pulse Current



Recommended Soldering Conditions

Reflow Soldering



Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	3°C/second max.
Preheat -Temperature Min ($T_{S\ min}$) -Temperature Max ($T_{S\ max}$) -Time (min to max) (t_s)	150°C 200°C 60-180 seconds
$T_{S\ max}$ to T_L -Ramp-up Rate	3°C/second max.
Time maintained above: -Temperature (T_L) -Time (t_L)	217°C 60-150 seconds
Peak Temperature (T_P)	260°C
Time within 5°C of actual Peak Temperature (t_p)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

Dimensions (SOT-523)

Symbol	Dimension			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.10	0.20	0.004	0.008
B	0.28	0.44	0.011	0.017
C	-	0.10	-	0.004
D	0.70	0.90	0.028	0.035
E	1.50	1.70	0.059	0.067
F	0.90	1.10	0.035	0.043
G	0.50TYP		0.020TYP	
H	0.75	0.85	0.030	0.033
I	1.45	1.75	0.057	0.069
J	0.15	0.35	0.006	0.014
h	0.70	0.80	0.028	0.031

Recommended Soldering Pad Layout

Packaging

Tape	Symbol	Dimension (mm)
	W	8.00±0.30
P0	4.00±0.10	
P1	4.00±0.10	
P2	2.00±0.10	
D0	Φ1.55±0.10	
D1	Φ0.50±0.05	
E	1.75±0.10	
F	3.50±0.10	
A	1.80±0.10	
A0	0.80±0.10	
B	1.80±0.10	
B0	0.45±0.10	
K	0.85±0.10	
t	0.20±0.05	

Reel	Symbol	Dimension (mm)
	D	Φ178.0±2.0
	D2	Φ13.0
W1	9.5	
Quantity: 3000PCS		